

Title (en)
HEAT-BONDABLE COMPOSITE FIBER AND PROCESS FOR PRODUCING THE SAME

Title (de)
THERMOBONDIERBARE VERBUNDFASER UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
FIBRE COMPOSITE THERMOSOUDABLE ET SON PROCÉDÉ DE PRODUCTION

Publication
EP 2022877 A1 20090211 (EN)

Application
EP 07743519 A 20070510

Priority
• JP 2007060084 W 20070510
• JP 2006133794 A 20060512

Abstract (en)
An essential object of the invention is to provide a low-modulus, self-extensible thermal-adhesive bicomponent fiber comprising polyethylene terephthalate as the fiber-forming resin component thereof and capable of producing a nonwoven fabric or a fiber structure that has a high adhesive strength and is bulky and well drapable. The object of the invention is attained by a self-extensible thermal-adhesive bicomponent fiber that comprises a fiber-forming resin component and a thermal-adhesive resin component and is characterized in that the fiber-forming resin component comprises polyethylene terephthalate, that the thermal-adhesive resin component comprises a crystalline thermoplastic resin having a melting point lower by at least 20 °C than that of the fiber-forming resin component, and that its breaking elongation is from 130 to 600 %, its 100 % elongation tensile strength is from 0.3 to 1.0 cN/dtex and its 120 °C dry heat shrinkage is smaller than -1.0 %; and by a method for producing it.

IPC 8 full level
D01F 8/14 (2006.01); **D02J 1/22** (2006.01); **D04H 1/541** (2012.01)

CPC (source: EP KR US)
D01D 5/34 (2013.01 - KR); **D01F 8/14** (2013.01 - EP KR US); **D02J 1/22** (2013.01 - EP KR US); **D04H 1/54** (2013.01 - EP US); **D04H 1/541** (2013.01 - KR); **Y10T 428/2929** (2015.01 - EP US); **Y10T 442/641** (2015.04 - EP US)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR MK RS

DOCDB simple family (publication)
EP 2022877 A1 20090211; **EP 2022877 A4 20090513**; **EP 2022877 B1 20100428**; AT E466122 T1 20100515; CN 101443491 A 20090527; CN 101443491 B 20111116; DE 602007006180 D1 20100610; HK 1127376 A1 20090925; HK 1129431 A1 20091127; JP 2007303035 A 20071122; JP 4820211 B2 20111124; KR 101357446 B1 20140203; KR 20090010229 A 20090129; MY 151200 A 20140430; RU 2008148973 A 20100620; RU 2440447 C2 20120120; TW 200809022 A 20080216; TW I410540 B 20131001; US 2009227166 A1 20090910; WO 2007132905 A1 20071122

DOCDB simple family (application)
EP 07743519 A 20070510; AT 07743519 T 20070510; CN 200780017154 A 20070510; DE 602007006180 T 20070510; HK 09105039 A 20090604; HK 09107464 A 20090813; JP 2006133794 A 20060512; JP 2007060084 W 20070510; KR 20087029803 A 20070510; MY PI20084316 A 20081029; RU 2008148973 A 20070510; TW 96116869 A 20070511; US 30042807 A 20070510